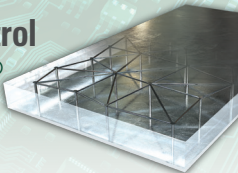


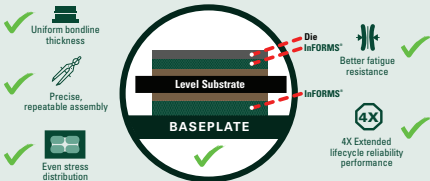
Proven Bondline Control InFORMS[®]



✓
InFORMS[®] was developed to realize superior solder joint reliability in power module applications:

- Standoff coverage across the entire assembly → Prevent tilt and stress concentration
- Integrated matrix adds strength → Solder creep resistance
- Precise, repeatable bondline thickness → Consistent soldering performance during production
- Wide range of alloys and configurations available → Drop-in replacement for solder preforms

BONDLINE CONTROL = BEST PERFORMANCE



InFORMS[®] are reinforced solder preforms that deliver a uniform bondline thickness after reflow

4X LONGER LIFECYCLE

Contact our engineers: askus@indium.com

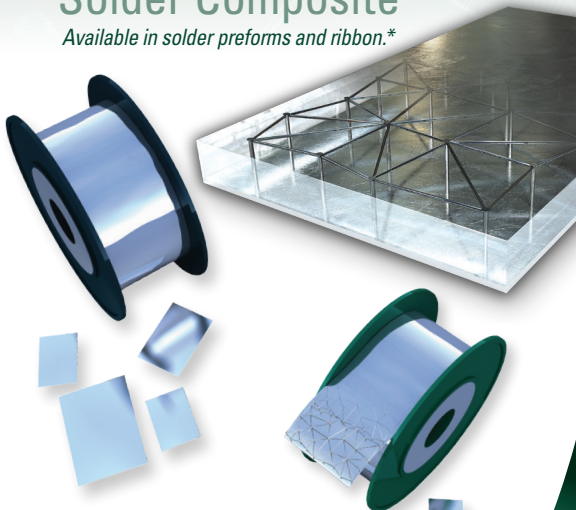
Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

InFORMS®

Reinforced Matrixed Solder Composite

*Available in solder preforms and ribbon.**



**Patent pending*

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